

ABSTRACT

A wiring substrate, in which a wiring stacked portion including a conductor layer and a resin layer is stacked on a principal face of a core substrate including a substantially cylindrical through hole conductor in a through hole extending therethrough and a filling material filling the hollow portion of said through hole, comprising: a cover-shaped conductor portion covering an end face of said through hole just over a principal face of said core substrate and connected to said through hole conductor; and an internal conductor layer provided in said wiring stacked portion and across at least one of said resin layer from said cover-shaped conductor layer, wherein a connection portion composed of via conductors buried in said resin layer brings said cover-shaped conductor portion and said internal conductor layer into conduction, and said via conductors composing said connection portion are provided not above said through hole.

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